IPC ASSOCIATION CONNECTED ELECTRONICS INDUST	Material Comp © Copyright 2005. I international and Par	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information			
upplier Info	rmation														
Company name* Compa			Company un	ompany unique ID			Unique ID Authority					Response Date*			
nsemi										2023-0	2023-06-08				
Contact Name		Title - Contact			I	Phone - Contact*				Email	Email - Contact*				
Product-Env-Ste	wards	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
uthorized Repr	esentative*	Title - Representative			I	Phone - Representative*				Email	Email - Representative*				
Product-Env-Ste	ewards	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
Reque	Requester Item Number		Number	Mfr Item Name			Effective Date	Version	n I	Manufacturing Site		Weight*	UOM	Unit Type	
		AP0202AT2L00XPG 2MP CO-PROCES A0-DR		ESSOR		2023-06-08	MY5			89.81	mg	Each			
Ianufacturin	g Proccess Informa	tion													
Terminal Plating / Grid Array Material Term			erminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Temperature Max Time at Peal			k Tempera	nture Numb	er of Reflow Cyc	eles			
SnAgCu		CU Alloy 3		3		260		С	30	seco	nds 3				
omments															
TTENTION: M	ISL 3 Rated item require	s Bake and I	Pack (after	electrical test)											
or more inform	ation regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.61	mg		Misc.	proprietary data		0.0192	mg
			Supplier	Silicon (Si)	7440-21-3		6.5842	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0066	mg
Die Attach	0.66	mg	Supplier	Epoxy resins	129915-35-1		0.0627	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.1947	mg
			Supplier	Acrylic resins	Proprietary Data		0.0957	mg
			Supplier	Polyimide	Proprietary Data		0.1947	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.1122	mg
Mold Compound-Black	43.67	mg		Phenolic Resin	proprietary data		2.0743	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		2.1835	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1092	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		39.303	mg
Solder Ball	10.46	mg	Supplier	Silver (Ag)	7440-22-4		0.3138	mg
			Supplier	Tin (Sn)	7440-31-5		10.0939	mg
			Supplier	Copper (Cu)	7440-50-8		0.0523	mg
Substrate and Solder Mask	27.33	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		5.7912	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		0.358	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0875	mg
			Supplier	Acetophenone Derivative	Proprietary Data		0.5357	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0902	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8		0.0902	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data		3.5748	mg
			Supplier	Formaldehyde Polymer	9003-36-5		1.0713	mg
			Supplier	Copper (Cu)	7440-50-8		12.9599	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		2.7713	mg
Wire Bond - Au	1.08	mg	Supplier	Gold (Au)	7440-57-5		1.08	mg